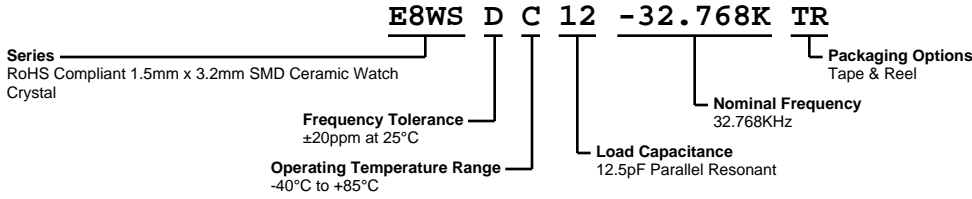


E8WSDC12-32.768K TR



ECLIPTEK
CORPORATION



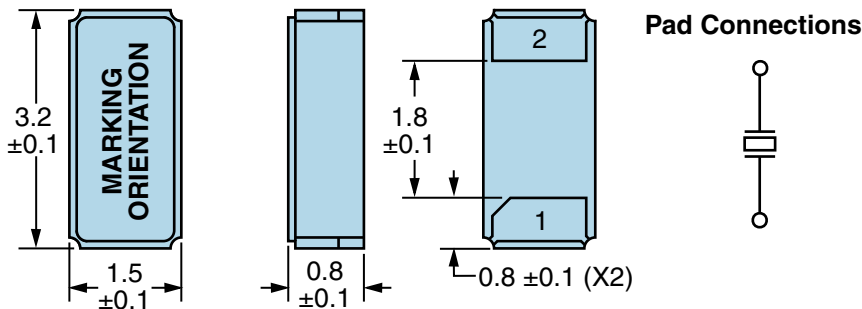
ELECTRICAL SPECIFICATIONS

Nominal Frequency	32.768KHz
Frequency Tolerance	±20ppm at 25°C
Frequency Stability	Parabolic -0.04ppm/(Change in °C) ² Maximum
Aging at 25°C	±3ppm/year Maximum
Operating Temperature Range	-40°C to +85°C
Load Capacitance	12.5pF Parallel Resonant
Shunt Capacitance (C0)	1.0pF Typical, 2pF Maximum
Motional Capacitance	3.4fF Typical
Equivalent Series Resistance	70,000 Ohms Maximum
Mode of Operation	Tuning Fork, Turn over Temperature at 25°C ±5°C
Drive Level	0.5µWatt Maximum
Storage Temperature Range	-55°C to +125°C
Insulation Resistance	500 Megaohms Minimum at 100VDC

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Solderability	MIL-STD-883, Method 2003
Vibration	MIL-STD-883, Method 2007, Condition A

MECHANICAL DIMENSIONS (all dimensions in millimeters)



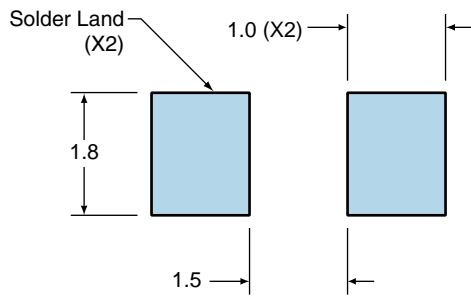
PIN	CONNECTION
1	Crystal
2	Crystal

LINE	MARKING
1	XXXXX XXXXX=Ecliptek Manufacturing Code

E8WSDC12-32.768K TR

Suggested Solder Pad Layout

All Dimensions in Millimeters

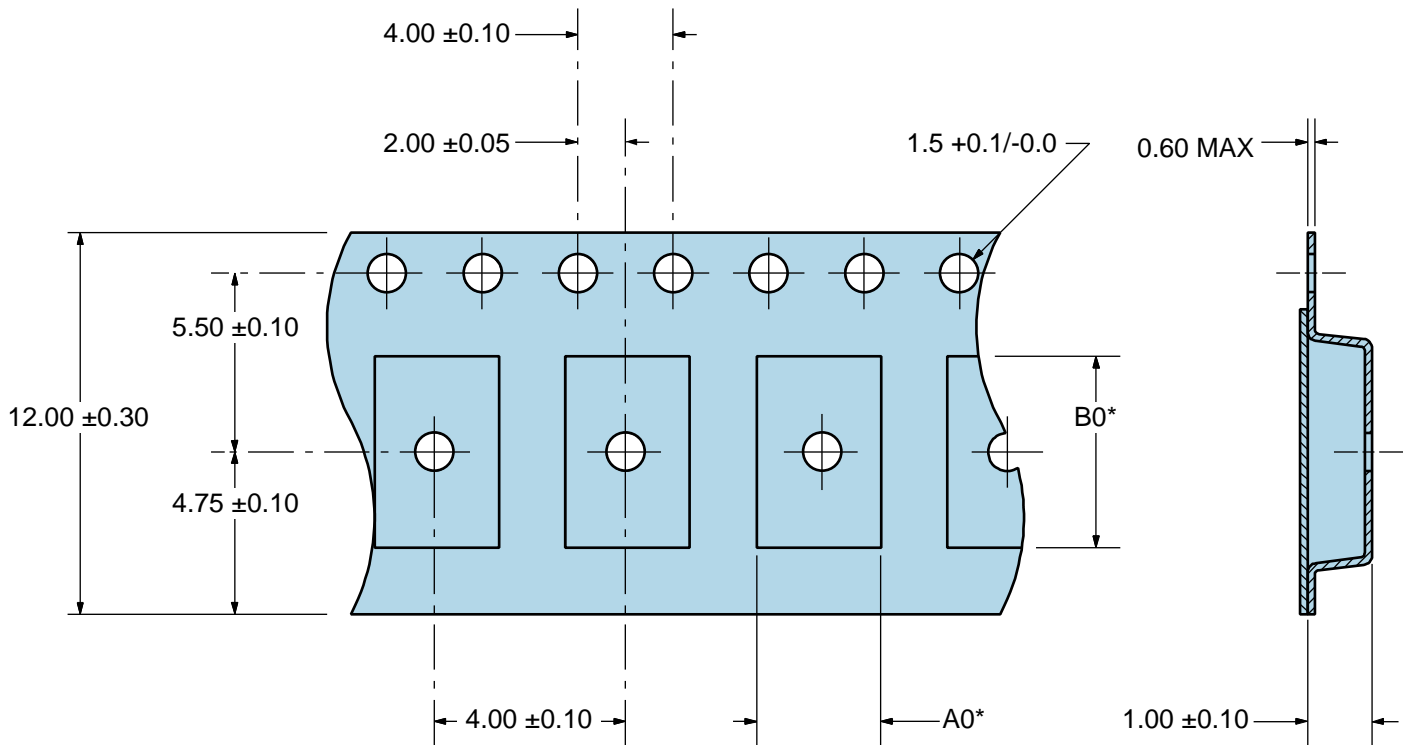


All Tolerances are ± 0.1

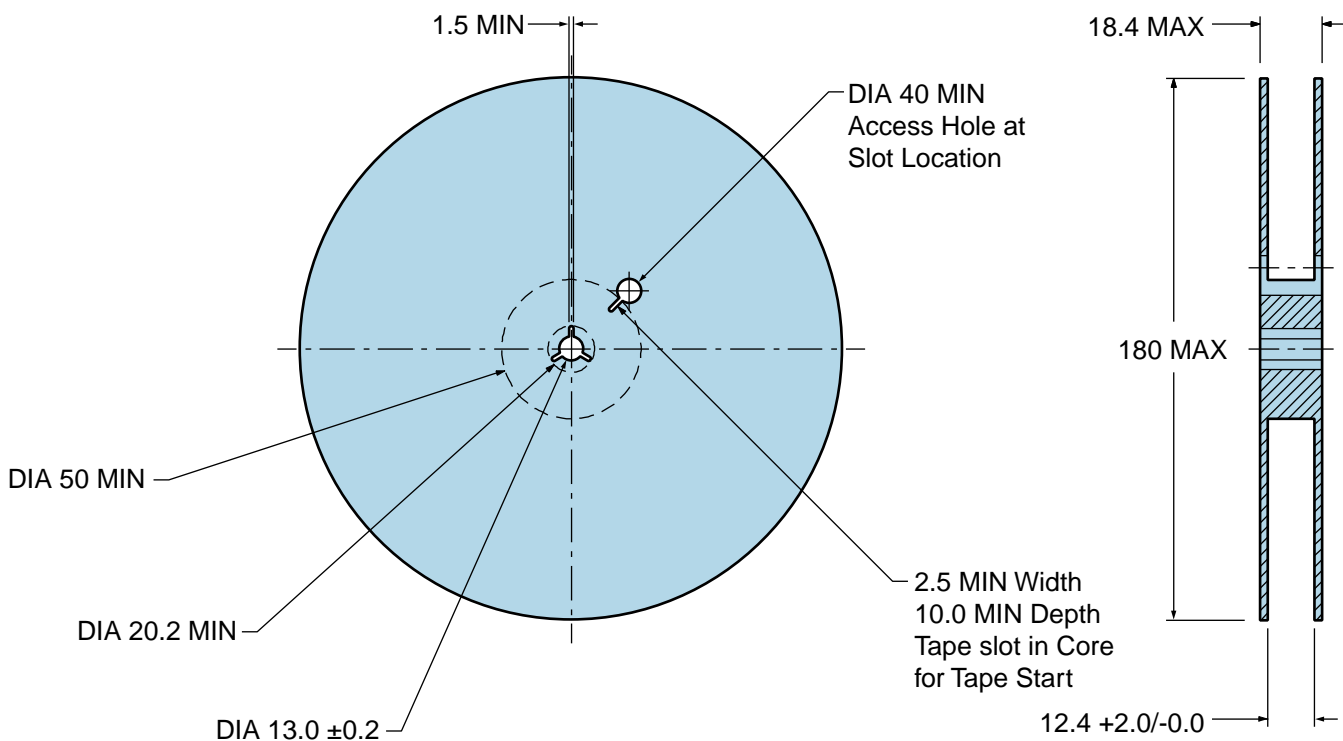
E8WSDC12-32.768K TR

Tape & Reel Dimensions

Quantity Per Reel: 3,000 units



*Compliant to EIA 481A



Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_s MAX to T_L (Ramp-up Rate)	3°C/second Maximum
Preheat	
- Temperature Minimum (T_s MIN)	150°C
- Temperature Typical (T_s TYP)	175°C
- Temperature Maximum (T_s MAX)	200°C
- Time (t_s MIN)	60 - 180 Seconds
Ramp-up Rate (T_L to T_p)	3°C/second Maximum
Time Maintained Above:	
- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds
Peak Temperature (T_p)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T_p Target)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 seconds
Ramp-down Rate	6°C/second Maximum
Time 25°C to Peak Temperature (t)	8 minutes Maximum
Moisture Sensitivity Level	Level 1

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

T_S MAX to T_L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _S MIN)	N/A
- Temperature Typical (T _S TYP)	150°C
- Temperature Maximum (T _S MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T_L to T_P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T _L)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T_P)	245°C Maximum
Target Peak Temperature (T_P Target)	245°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (t_p)	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.